

Amendment to the Claims

Following is a complete listing of the claims pending in the application, as amended:

1. (Original) An image sensor comprising:
a plurality of pixels formed in a semiconductor substrate, each pixel including a light sensitive element;
a micro-lens over each of said light sensitive elements; and
a trench structure surrounding each of said micro-lenses.
2. (Original) The image sensor of Claim 1 wherein said trench structure is circular.
3. (Original) The image sensor of Claim 1 wherein said trench structure has a rectangular cross-section.
4. (Original) The image sensor of Claim 1 wherein the micro-lenses are formed from polymethylmethacrylate (PMMA) or polyglycidylmethacrylate (PGMA).
5. (Original) The image sensor of Claim 1 wherein said trench structure has a depth on the order of 0.2 microns.
6. (Original) The image sensor of Claim 1 wherein said trench structure is formed in a layer that underlies said micro-lenses.
7. (Original) The image sensor of Claim 1 further including a color filter layer between said micro-lenses and said light sensitive elements.

8. (Original) A pixel of an image sensor comprising:
a light sensitive element formed in a semiconductor substrate;
a micro-lens over said light sensitive element; and
a trench structure surrounding said micro-lens.
9. (Original) The pixel of Claim 8 wherein said trench structure is circular.
10. (Original) The pixel of Claim 8 wherein said trench structure has a rectangular cross-section.
11. (Original) The pixel of Claim 8 wherein the micro-lens is formed from polymethylmethacrylate (PMMA) or polyglycidylmethacrylate (PGMA).
12. (Original) The pixel of Claim 8 wherein said trench structure has a depth on the order of 0.2 microns.
13. (Original) The pixel of Claim 8 wherein said trench structure is formed in the material that underlies said micro-lenses.
14. (Original) The pixel of Claim 8 further including a color filter layer between said micro-lenses and said light sensitive elements.
15. – 19. (Cancelled)